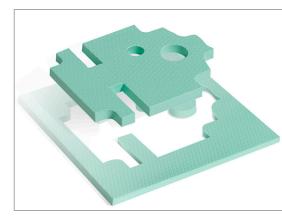
THERM-A-GAP™ PAD 60

ULTRA-SOFT, 6.0 W/m-K THERMALLY CONDUCTIVITY GAP FILLER PAD



Customer Value Proposition:

Parker Chomerics THERM-A-GAP™ PAD 60 is an ultra-soft, ultra-conformable high performance thermally conductive gap filler pad with 6.0 W/m-K thermal conductivity.

THERM-A-GAP PAD 60 offers the combination of both excellent thermal conductivity and ultra-soft conformability, along with very low outgassing to provide an effective thermal interface between heat sinks and electronic devices where there are uneven surfaces, air gaps and rough surface textures may exist.

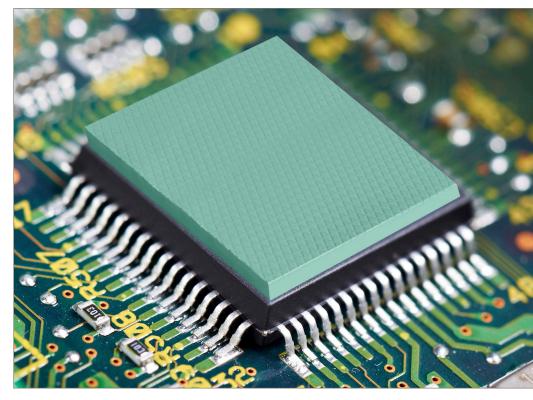
THERM-A-GAP PAD 60 is manufactured to size and facilitates easy application on the desired component.

Contact Information:

Parker Hannifin Corporation Parker Chomerics 77 Dragon Court Woburn, MA 01801

phone 781 935 4850 fax 781 933 4318 chomailbox@parker.com

www.parker.com/chomerics



Product Features:

- 6.0 W/m-K thermal conductivity
- Ultra low deflection force
- High thermal conductivity
- "A" version offers high strength acrylic PSA for permanent attachment
- UL recognized V-0 flammability RoHS compliant

Typical Applications:

- 5G telecom equipment
- Smart home devices
- Automotive electronics (ECUs)
- LEDs
- Power supplies
- Desktop computers, laptops, servers
- Handheld devices
- Memory modules
- Vibration dampening



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Product Information THERM-A-GAP PAD 60

	Typical Properties [†]	PAD 60	Test Method
	Color	Green	Visual
Physical	Carrier Options: A= Aluminum foil w/ pressure sensitive adhesive None (unsupported) = No letter suffix	PAD60A PAD60	
	Standard Thicknesses*, in. (mm)	0.020 - 0.200 (0.50 - 5.0)	ASTM D374
	Specific Gravity	3.3	ASTM D792
	Hardness, Shore 00	31	ASTM D2240
	Percent Deflection @ Various Pressures** (0.100 in thick sample) @ 5 psi (34 kPa) @ 10 psi (69 kPa) @ 25 psi (172 kPa) @ 50 psi (345 kPa)	% Deflected 12 17 27 38	ASTM C165 MOD (0.100 in "A" Carrier, 0.50 in dia. probe, 0.025 in/min rate)
Thermal	Operating Temperature Range, °F (°C)	-67 to 392 (-55 to 200)	Chomerics
	Thermal Conductivity, W/m-K	6.0	ASTM D5470
	Thermal Impedance, °C-in²/W (°C-cm²/W) @ 10 psi, @ 0.04 in. (1mm) thick, "G" version	0.2 (1.5)	ASTM D5470
	Heat Capacity, J/g-K	1	ASTM E1269
	Coefficient of Thermal Expansion, ppm/K	150	ASTM E831
Electrical	Dielectric Strength, VAC/mil (KVAC/mm)	127 (5.0)	ASTM D149
	Volume Resistivity, ohm-cm	10 ¹³	ASTM D257
	Dielectric Constant @ 1,000 kHz	9.3	ASTM D150
	Dissipation Factor @ 1,000 kHz	0.006	Chomerics
Regulatory	Flammability Rating (See UL File E140244 for Details)	V-0	UL 94
	RoHS Compliant	Yes	Chomerics Certification
	Outgassing, % TML (% CVCM)	0.05 (0.01)	ASTM E595
	Shelf Life, months from date of shipment (PAD60A)	36 (18)	Chomerics
	Storage Conditions, °F (°C) @ 50% Relative Humidity	50 to 90 (10 to 32)	Chomerics

† Typical properties: these are not to be construed as specifications.

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K. R. Anderson, Inc. www.krafab.com 408-825-1900



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